# No Problem!

## HLC Hybrid Light-Curable Technology

Dymax HLC<sup>™</sup> adhesives cure with or without light, quickly bonding a wide range of materials, including opaque or light-blocking substrates.

### **Key Attributes**

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- Optimized for 405 nm LED curing, but is also cures fast and tack free with either LED or broad spectrum

On-contact dark area cure capability

Low to no blooming after proper light cure



Cures with very low intensity  $(\sim 20 \text{ mW/cm}^2)$ 

Heat and humidity resistance

ISO 10993 compliant (/)

#### **The Chemistry Behind HLC**

A revolutionary patent-pending adhesive platform, HLC technology combines the best qualities of anionic and free radical chemistries. HLC adhesives exhibit the exceptional physical and performance properties of Dymax light-curable adhesives and the rapid moisture/contact cure of anionics.

Anionic [Linear Polymer]

Free Radical [Crosslinked Polymer]

#### **How Does HLC Compare to Similar Technologies?**

	Dymax Light-Curable Material	Dymax HLC™ Material	Cyanoacrylate
Fast Cure Speeds	Full cure in 1-30 sec.	Light cure in 1-30 sec.; Non-light fixture in 5-75 sec.	Fixture only in 10-60 sec.
Tack-Free Surface Cure	Specific formulas only; Can require high-intensity light cure	Tack free with low intensity light (20 mW/cm²) <5 seconds	Specific formulas only; Requires use of activators
<b>Open Time</b> (Time Before Cure Begins)	No cure until exposed to high-intensity light	10-30 seconds	10-30 seconds
Moisture Resistance	Some with excellent moisture resistance	Patented technology to increase moisture resistance	Not designed for high humidity or long-term moisture exposure
Temperature Resistance	Can withstand greater temperature extremes or a broader range of temperatures	Patented technology to increase temperature resistance	Not recommended for ≥225°F (107°C)
Opaque Substrate Bonding	Opaque substrates block UV and visible light	Not an issue	Not an issue
Impact Resistance	Grades range from flexible to rigid	Patented technology to reduce brittleness and increase impact resistance	Brittle with little impact resistance
UV/LED Light-Curing Equipment	Light-curing equipment required	Equipment can be used to improve cure time and reduce crazing but not required for dark areas	No equipment required
Gap Cure	Typically recommended for 0.002"-0.25" (0.05-6.35 mm) with some formulas able to provide even larger gap curing	Can accommodate close gaps or larger bond gaps with light cure	Requires close contact
Blooming	Not an issue	Low to no blooming after proper cure	Produces white haze around bond line during or after the cure





Dymax manufactures light-curable adhesives, coatings, and maskants, as well as compatible dispensing and curing equipment. We focus on creating materials that cure clean, green, and fast, helping engineering teams accomplish more in less time and with less negative impact on the environment.

#### www.dymax.com